

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claim 1 (Currently amended): A method of probing an electronic device, said electronic device comprising a surface ~~[[and]]~~ comprising a plurality of terminals, said method comprising:

positioning said electronic device and a plurality of probes in a first relative position such that said probes are adjacent ones of said terminals; and

effecting relative movement of said electronic device and said probes to bring said ~~ones of said terminals into contact with~~ electronic device and said probes into a second relative position,

wherein:

in said first relative position, said probes are spaced apart from said electronic device,

in said second relative position, ones of said probes physically contact ones of said terminals, and

said relative movement comprises a directional component that is parallel to said surface of said electronic device.

Claim 2 (Currently amended): The method of ~~claim 1~~ claim 3, wherein said ~~ones of said~~ terminals extend from said surface of said electronic device by a distance "d," and said ~~step of~~ positioning said electronic device and a plurality of probes comprises positioning contact portions of said ~~[[tips]]~~ probes less than said distance "d" from said surface of said electronic device.

Claim 3 (Currently amended): ~~The method of claim 1, wherein~~ A method of probing an electronic device, said electronic device comprising a surface and a plurality of terminals, said method comprising:

positioning said electronic device and a plurality of probes such that said probes are adjacent ones of said terminals; and

effecting relative movement of said electronic device and said probes to bring said ones of said terminals into contact with said probes,

wherein said relative movement comprises a component that is parallel to said surface of said electronic device, and

said terminals comprise elements ~~raised above~~ that extend from the surface of the electronic device.

Claim 4 (Original): The method of claim 1, wherein said terminals comprise flat pads.

Claim 5 (Currently amended): The method of ~~claim 1~~ claim 3, wherein said terminals comprise partial spheres.

Claim 6 (Currently amended): ~~The method of claim 1, wherein~~ A method of probing an electronic device, said electronic device comprising a surface and a plurality of terminals, said method comprising:

positioning said electronic device and a plurality of probes such that said probes are adjacent ones of said terminals; and

effecting relative movement of said electronic device and said probes to bring said ones of said terminals into contact with said probes,

wherein said relative movement comprises a component that is parallel to said surface of said electronic device and each said probe comprises a plurality of tips.

Claim 7 (Currently amended): The method of claim 1, wherein said relative movement further comprises a directional component that is perpendicular to said surface of said electronic device.

Claim 8 (Currently amended): The method of claim 1 further comprising testing said electronic device while said ones of said probes are in contact with said ones of said terminals.

Claim 9 (Original): The method of claim 1, wherein said electronic device comprises a semiconductor device.

Claim 10 (Original): The method of claim 1, wherein said electronic device comprises a semiconductor wafer.

Claim 11 (Currently amended): The method of ~~claim 1~~ claim 31, wherein said electronic device comprises a package for a semiconductor device.

Claim 12 (Currently amended): The method of ~~claim 1~~ claim 31, wherein said electronic device comprises a package for a plurality of semiconductor devices.

Claim 13 (Original): The method of claim 1, wherein said electronic device comprises a semiconductor die.

Claim 14 (Original): The method of claim 1, wherein said electronic device comprises a plurality of semiconductor dies.

Claim 15 (Currently amended): The method of ~~claim 1~~ claim 31, wherein said electronic device comprises a printed circuit board.

Claim 16 (Currently amended): The method of ~~claim 1~~ claim 31, wherein said electronic device comprises a ceramic space transformer.

Claim 17 (Currently amended): The method of ~~claim 1~~ claim 31, wherein said electronic device comprises[[:]] a wiring board; ~~and~~ to which a plurality of semiconductor devices are electrically connected ~~to said wiring board~~.

Claim 18 (Currently amended): ~~A media containing machine-executable instructions for causing a controller to perform a method of controlling a probing machine, said probing machine comprising a chuck, said method comprising:~~ A program product for use in conjunction with a probing machine, the program product comprising a readable storage medium and a program mechanism embedded therein, the program mechanism comprising:

instructions for generating first signals to position [[said] an electronic device and a plurality of probes such that said probes are adjacent terminals of an electronic device disposed on said chuck in a first relative position; and

instructions for generating second signals effecting relative movement of said electronic device and said probes to bring said terminals into contact with electronic device and said probes into a second relative position,

wherein:

in said first relative position, said probes are spaced apart from said electronic device,

in said second relative position, ones of said probes physically contact ones of terminals composing a surface of said electronic device, and

said relative movement comprises a directional component that is parallel to said surface of said electronic device.

Claim 19 (Currently amended): ~~The media of claim 18, wherein~~ A program product for use in conjunction with a probing machine, the program product comprising a readable storage medium and a program mechanism embedded therein, the program mechanism comprising:

instructions for generating first signals to position an electronic device and a plurality of probes such that said probes are adjacent terminals composing a surface of said electronic device; and

instructions for generating second signals effecting relative movement of said electronic device and said probes to bring said terminals into contact with said probes,

wherein said relative movement comprises a component that is parallel to said surface of said electronic device, and

said terminals extend from a surface of said electronic device by a distance "d," and said ~~step of generating first signals comprises positioning~~ position contact portions of said ~~[[tips]]~~ probes less than said distance "d" from said surface of said electronic device.

Claim 20 (Currently amended): ~~The media of claim 18, wherein~~ A program product for use in conjunction with a probing machine, the program product comprising a readable storage medium and a program mechanism embedded therein, the program mechanism comprising:

instructions for generating first signals to position an electronic device and a plurality of probes such that said probes are adjacent terminals of said electronic device disposed on said chuck; and

instructions for generating second signals effecting relative movement of said electronic device and said probes to bring said terminals into contact with said probes,

wherein said relative movement comprises a component that is parallel to said surface of said electronic device and each said probe comprises a plurality of tips.

Claim 21 (New): The program product of claim 18, wherein said second signals move at least one of said probes or said electronic device in a single direction without changing said single direction.

Claim 22 (New): The program product of claim 18, wherein said second signals move said electronic device in a single direction without changing said single direction.

Claim 23 (New): The program product of claim 18, wherein said second signals move at least one of said probes or said electronic device in a straight line from said first relative position to said second relative position.

Claim 24 (New): The program product of claim 18, wherein said second signals move said electronic device in a straight line from said first relative position to said second relative position.

Claim 25 (New): The program product of claim 18, wherein said first signals and said second signals control movement of a chuck on which said electronic device is disposed, and said probes are not moved.

Claim 26 (New): The method of claim 1, wherein said effecting step comprises moving at least one of said probes or said electronic device in a single direction without changing said single direction.

Claim 27 (New): The method of claim 1, wherein said effecting relative movement comprises moving said electronic device in a single direction without changing said single direction.

Claim 28 (New): The method of claim 1, wherein said effecting relative movement comprises moving at least one of said probes or said electronic device in a straight line from said first relative position to said second relative position.

Claim 29 (New): The method of claim 1, wherein said effecting relative movement comprises moving said electronic device in a straight line from said first relative position to said second relative position.

Claim 30 (New): The method of claim 1, wherein:

said positing in a first relative position said electronic device and a plurality of probes comprises moving said electronic device without moving said probes, and

said effecting relative movement of said electronic device and said probes comprises moving said electronic device without moving said probes.

Claim 31 (New): A method of probing an electronic device, said electronic device comprising a surface and a plurality of terminals, said method comprising:

positioning said electronic device and a plurality of probes such that said probes are adjacent ones of said terminals; and

effecting relative movement of said electronic device and said probes to bring said ones of said terminals into contact with said probes,

wherein said relative movement comprises a component that is parallel to said surface of said electronic device, and

said electronic device comprises one of a package for a semiconductor device, a package for a plurality of semiconductor devices, a printed circuit board, a ceramic space transformer, and a wiring board to which a plurality of semiconductor devices are electrically connected.